

NOELLE DAVIS

[✉ noelledavis@berkeley.edu](mailto:noelledavis@berkeley.edu)

[🌐 noelledavis.github.io/](https://noelledavis.github.io/)

[🔗 github.com/noelledavis](https://github.com/noelledavis)

New PhD graduate in wearable electronics. Interested in full-time opportunities developing sensing systems in Fall 2025.

Education	University of California, Berkeley Berkeley, CA <i>Laboratory for Materials and Device Innovation, advised by Dr. Ali Javey</i> Ph.D. Electrical Engineering and Computer Science Dissertation: Wearable, User-Centric Sweat Sensing Platforms with Scalable Fabrication	August 2025
	California Institute of Technology Pasadena, CA B.S. Electrical Engineering GPA: 3.80/4.00	June 2020
Experience	Laboratory for Materials and Device Innovation, UCB Berkeley, CA <i>Doctoral Researcher</i> <ul style="list-style-type: none">Designed complete wearable platforms for sensing eccrine sweat integrating microfluidics, electrochemical sensors, PCB's, and packaging which outperform precision of commercial devices.Fabricated devices via laser cutting, 3D printing, and roll-to-roll screen printing on PET and TPU films. Department of Electrical Engineering and Computer Sciences, UCB Berkeley, CA <i>Graduate Student Instructor</i> CS 61C, Introduction to Computer Architecture, Discussion TA, 3x guest lectures (1 semester) EECS 16B, Designing Information Devices and Systems II, Head TA, 3x guest lectures (2 semesters) EECS 149/249a, Introduction to Embedded Systems, Laboratory TA (1 semester) <i>Awarded Certificate in Teaching and Learning in Higher Education by GSI Teaching & Resource Center</i>	Aug 2020 – Aug 2025
	VTT Technical Research Centre, Flexible Sensors & Devices Espoo, Finland <i>Visiting Researcher</i> <ul style="list-style-type: none">Iterated on roll-to-roll screen printing of electrode patterns on TPU resulting in 2x improved yield.Characterized flexible electrodes under linear strain, demonstrating stability up to 15% strain.	Aug 2023 – Dec 2023
	Department of Electrical Engineering, Caltech Pasadena, CA <i>Undergraduate Teaching Assistant</i> EE 10a, Introduction to Embedded Systems I (2 quarters) EE 10b, Introduction to Embedded Systems II (2 quarters) EE 13, Electrical Prototyping (1 quarter) EE/ME 7, Intro to Mechatronics (1 quarter)	Sep 2018 – June 2020
	NASA Jet Propulsion Laboratory Pasadena, CA <i>Electrical Systems Engineering Intern</i>	Jun 2019 – Aug 2019
	Velodyne LiDAR Alameda, CA <i>Electrical Engineering Intern</i>	Jun 2018 – Aug 2018
	Nanofabrication Group, Caltech Pasadena, CA <i>Undergraduate Researcher</i>	Mar 2017 – Jun 2020
Awards and Fellowships	2024 Best Oral Presentation, Berkeley Sensors and Actuators Conference. <i>Industry member vote.</i> 2023 Grasshopper 5-Race Series Champion, Amateur Women 20-29. <i>Gravel and mountain biking.</i> 2021 National Defense Science and Engineering Graduate (NDSEG) Fellowship 2021 National Science Foundation (NSF) Graduate Research Fellowship (declined) 2020 Caltech Deans' Office Robert L. Noland Leadership Award. <i>Motivating others in leadership.</i> 2020 Caltech Athletics Director's Award. <i>Annual female awardee.</i> 2019 Caltech Deans' Office Donald S. Clark Service Award. <i>Service & academic excellence.</i> 2019 Southern California Intercollegiate Athletics Conference Women's Soccer Award of Distinction	
Invited Talks	Berkeley Institute of Design, Summer Design Seminar BMW Technology Office, "Unlocking Insights with Biosensors" Workshop Berkeley Sensors and Actuators Center Research Review	July 2025 February 2025 March 2024

Publications	<p>sNails: Sweat-Sensing Nails for Unobtrusive, Wearable Microfluidic Sweat Monitoring on the Dorsal Distal Phalanges. Noelle Davis, Pooja Mehta, Amanda Kang, Liam Gillan, Jussi Hiltunen, and Ali Javey. <i>Lab on a Chip</i>. 2025.</p> <p>Reusable, Fully Integrated Sweat Monitor Band with Peel-and-Stick-Replacement Printed Microfluidic Sensor. Noelle Davis, Amanda Kang, Elina Hakola, Liam Gillan, Yifei Zhan, Jussi Hiltunen, and Ali Javey. <i>Advanced Materials Technologies</i>. 2025.</p> <p>Electrodermal Activity as a Proxy for Sweat Rate Monitoring during Physical and Mental Activities. Seung-Rok Kim*, Yifei Zhan*, Noelle Davis*, Suhrit Bellamkonda, Liam Gillan, Elina Hakola, Jussi Hiltunen, and Ali Javey. <i>Nature Electronics</i>. 2025.</p> <p>The Challenges and Promise of Sweat Sensing. Noelle Davis, Jason Heikenfeld, Carlos Milla, and Ali Javey. <i>Nature Biotechnology</i>. 2024.</p> <p>Tape-Free, Digital Wearable Band for Exercise Sweat Rate Monitoring. Manik Dautta, Luis Fernando Ayala-Cardona, Noelle Davis, Ashwin Aggarwal, Jonghwa Park, Shu Wang, Liam Gillan, Elina Jansson, Mikko Hietala, Hyunhyub Ko, Jussi Hiltunen, and Ali Javey. <i>Advanced Materials Technologies</i>. 2023.</p> <p>DeTagTive: Linking MACs to Protect Against Malicious BLE Trackers. Tess Despres, Noelle Davis, Prabal Dutta, David Wagner. <i>SNIP2+: Proceedings of the Second Workshop on Situating Network Infrastructure with People, Practices, and Beyond</i>. 2023.</p> <p>Resettable Microfluidics for Broad-Range and Prolonged Sweat Rate Sensing. Mallika Bariya*, Noelle Davis*, Liam Gillan, Elina Jansson, Annukka Kokkonen, Colm McCaffrey, Jussi Hiltunen, and Ali Javey. <i>ACS Sensors</i>. 2022.</p> <p>A Wearable Patch for Continuous Analysis of Thermoregulatory Sweat at Rest. Hnin Yin Yin Nyein, Mallika Bariya, Brandon Tran, Christine Heera Ahn, Brenden Janatpour Brown, Wenbo Ji, Noelle Davis, and Ali Javey. <i>Nature Communications</i>. 2021.</p>																
	* indicates equal contribution																
Advising	<table> <tbody> <tr> <td>Luis Fernando Ayala Cardona (now PhD student at Northwestern University)</td> <td>spring 2021 – fall 2022</td> </tr> <tr> <td>Ashwin Aggarwal (now software engineer at Salesforce)</td> <td>fall 2021 – spring 2023</td> </tr> <tr> <td>Yifei Zhan (now PhD student at UC Berkeley)</td> <td>spring 2023 – fall 2023</td> </tr> <tr> <td>Nicole Qing (now PhD student at Northwestern University)</td> <td>summer 2023 – spring 2024</td> </tr> <tr> <td>Kalynna Tang</td> <td>fall 2023 – spring 2024</td> </tr> <tr> <td>Meera Devine (Bakar Ignite Scholar)</td> <td>spring 2024 – fall 2024</td> </tr> <tr> <td>Amanda Kang (Bakar Ignite Scholar)</td> <td>spring 2024 – spring 2025</td> </tr> <tr> <td>Pooja Mehta</td> <td>fall 2024 – spring 2025</td> </tr> </tbody> </table>	Luis Fernando Ayala Cardona (now PhD student at Northwestern University)	spring 2021 – fall 2022	Ashwin Aggarwal (now software engineer at Salesforce)	fall 2021 – spring 2023	Yifei Zhan (now PhD student at UC Berkeley)	spring 2023 – fall 2023	Nicole Qing (now PhD student at Northwestern University)	summer 2023 – spring 2024	Kalynna Tang	fall 2023 – spring 2024	Meera Devine (Bakar Ignite Scholar)	spring 2024 – fall 2024	Amanda Kang (Bakar Ignite Scholar)	spring 2024 – spring 2025	Pooja Mehta	fall 2024 – spring 2025
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